

BONDING THE STARS

FMS
BONDTEC



5810

Gold Ball Bonder

Bond System

Wire types	Goldwire 17,5 ... 50 µm on 2" spool motorized wire despooler (optional)
Bond head	Ball-Wedge for Au-wire Standard capillaries of 16mm length, optionally up to 19 mm
Ultrasonic System	F&K Generator 60 kHz / 100 kHz (further frequencies on request)

Bonder Base

Axes	Working area X/Y-axis 200 x 150 mm; step resolution 2 µm Programmable Z axis with 100 mm stroke; step resolution 1 µm
Hardware	Dual-Core PC with Windows 7 OS, Ethernet, USB 2.0/3.0 LCD Colour Display 22" GigE-CCD-Colour Camera, 5 Mpixel Fully networkable in TCP/IP servers for program archiving

Software	From single bonds up to complex programmes, teach-in programming, also in step-and-repeat Loop shapes can be stored in libraries Optionally: pattern recognition with pseudo-error check
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The Gold wire Ball-Wedge version of the automatic wire bonders in our Series 58 featuring exchangeable bond heads.

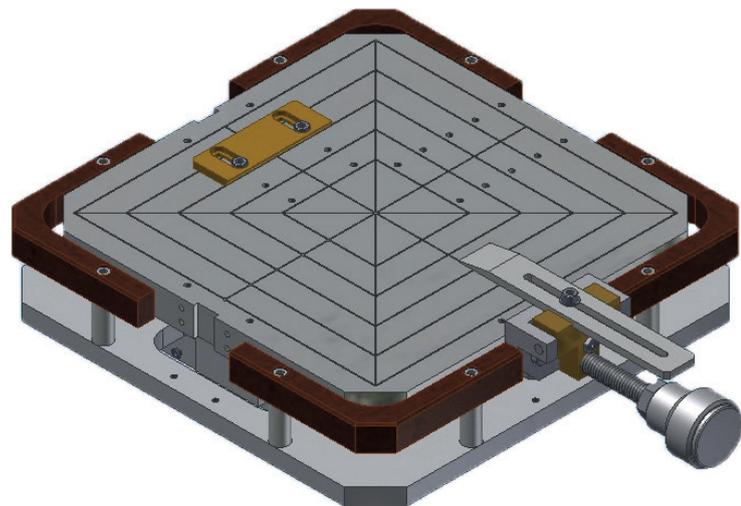
A fully automatic mode makes it ideally suited for medium-scale production. Parts to be bonded are fed manually by the operator, but the bonds are produced completely without operator influence. Thanks to the built-in pattern recognition.

Single bonds can be made within seconds, making the machine perfect for R&D and pilot manufacturing

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F&S BONDTEC

Dimensions W x D x H 92 x 71 x 65 cm, weight approx. 80 kg
Connections 100...240 VAC, single phase, 50/60 Hz, max. 230 VA
Heater control Ø 6 mm standard vacuum tubing integrated in the machine 0-300°C
Workholder



Standard-Workholder
for parts up to 6" x 6"
with Vacuum und mechanical clamping

Optional:



or parts up to 4 x 4"
with Vacuum and mechanical
clamping



TO Workholder
with mechanical clamping



DIL Workholder with vacuum
and mechanical clamping



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